ABSTRACT

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH PACKAGE-ON-PACKAGE STACKING AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit packaging system includes: forming a top package including: providing a through silicon via interposer having a through silicon via; coupling a stacked integrated circuit die to the through silicon via, and testing a top package; forming a base package including: providing a substrate, coupling a base integrated circuit die to the substrate, and testing a base package; and coupling a stacked interconnect between the top package and the base package.

(Fig.1)